



BRIGHTTEK

BRIGHTTEK (EUROPE) LIMITED

Brighten up The World With LED!



ISO/TS 16949:2009



BS EN ISO 14001:2004



QC 90000 IECQ HS1998

PRODUCT DATASHEET



- ▶ DC Input Photo Coupler
- ▶ LSOP6 (11mm clearance)
- ▶ High Speed Logic Gate 10Mbit/s

TDL601(W)(T3)-GV



Release Date: 20 July 2025 Version: A00



TDL601(W) Series

DESCRIPTION:



The TDL601(W) series combines an AlGaAs infrared emitting diode as the emitter which is optically coupled to a silicon high speed integrated photo-detector logic gate with a strobable output in a plastic LSOP6 package.

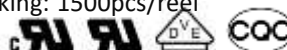
With the robust coplanar double mold structure, TDL601(W) series provide the most stable isolation feature.

FEATURES:

APPLICATIONS:

- Ground loop elimination
- LSTTL to TTL, LSTTL, or CMOS
- Line receiver, data transmission
- Data multiplexing
- Switching power supply
- Pulse transformer replacement
- Computer-peripheral interface

- High isolation 5000Vrms
- DC input with logic gate output
- Operating temperature range -55°C to +100°C
- REACH & RoHS compliance; Halogen Free
- MSL class 1
- Regulatory Approvals:
 - UL - UL1577
 - VDE - EN60747-5-5 (VDE0884-5)
 - CQC - GB4943.1, GB8898
 - cUL - CSA Component Acceptance Service Notice 5A
- Packing: 1500pcs/reel



Partner with:  LIGHTNING

NAMING & ORDERING INFORMATION:

Naming Information:

TDL601 (W) (T3) - G V	
TDL601	Part Number
W	Lead Form Option: LSOP6 P Type (11mm clearance)
T3	Selection: Tape and Reel Option
G	Green Option
V	VDE Option

Ordering Information:

TDL601(W)(T3)-GV

Version No.	Original Release Date
Rev: A00	10/10/2024

SCHEMATIC DIAGRAM & MARKING:

Schematic Diagram:

PIN Definition	
1	Anode
2	NC
3	Cathode
4	GND
5	VO
6	VCC

Marking Information:

Marking Definition	
TD	Manufacturer Code
601	Part Number
V	VDE Applicable
Y	Fiscal Year
A	Manufacturing Code
WW	Work Week

Labelling Information:

 Part No.: XXXXXXXXXXXX Bin Code: X Lot No.: XXXXXXXX Date Code: XXXX QTY: XXX PCS MSL: 1 Made in Quanzhou Fujian 	This product is manufactured by  for Brighttek (Europe) Limited
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ABSOLUTE CHARACTERISTICS:

Absolute Maximum Ratings:

Parameter	Symbol	Ratings	Unit
INPUT			
Forward Current	I_F	25	mA
Peak Forward Current	I_{FP}	50 * ¹	mA
Peak Transient Current	$I_{F(trans)}$	1 * ²	A
Reverse Voltage	V_R	5	V
Input Power Dissipation	P_I	100	mW
OUTPUT			
Supply Voltage	V_{CC}	7	V
Output Voltage	V_O	7	V
Output Current	I_O	50	mA
Output Power Dissipation	P_O	85	mW
COMMON			
Total Power Dissipation	P_{tot}	200	mW
Isolation Voltage	V_{iso}	5000 * ³	V _{rms}
Operating Temperature	T_{opr}	-55~+100	°C
Storage Temperature	T_{stg}	-55~+125	°C
Soldering Temperature	T_{sol}	260 * ⁴	°C

*1. 50% duty, 1ms P.W.

*2. $\leq 1\mu s$ P.W, 300pps.

*3. AC for 1 minute, R.H.=40~60%.

*4. For 10 seconds.

ELECTRICAL CHARACTERISTICS:

Recommended Operation Conditions:

Parameter	Symbol	Ratings			Unit
		Min.	Typ.	Max.	
Operating Temperature	T_a	-40	---	100	°C
Supply Voltage	V_{CC}	2.7	---	3.6	V
		4.5	---	5.5	
Low Level Input Current	I_{FL}	0	---	250	μA
High Level Input Current	I_{FH}	5	---	15	mA
Output Pull-up Resistor	R_L	330	---	4k	Ω
Fan Out (at $R_L=1k\Omega$ per channel)	N	---	---	5	TTL Loads

ELECTRICAL CHARACTERISTICS:

Electrical Optical Characteristics at $T_a=25^{\circ}\text{C}$:

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
INPUT						
Forward Voltage	V _F	---	1.38	1.8	V	I _F =10mA
Reverse Current	I _R	---	---	10	μA	V _R =5V
Input Capacitance	C _{IN}	---	13	---	pF	V=0, f=1MHz
OUTPUT						
High Level Supply Current	I _{CCH}	---	6.3	10	mA	I _F =0mA, V _{CC} =5.5V
Low Level Supply Current	I _{CCL}	---	8.3	13	mA	I _F =10mA V _{CC} =5.5V
TRANSFER CHARACTERISTICS (T _a =-40 to 85°C)						
High Level Output Current	I _{OH}	---	0.73	100	μA	V _{CC} =V _O =5.5V I _F =250μA
Low Level Output Voltage	V _{OL}	---	0.28	0.6	V	V _{CC} =5.5V, I _F =5mA I _{CL} =13mA
Input Threshold Current	I _{FT}	---	2.5	5	mA	V _{CC} =5.5V, V _O =0.6V I _{OL} =13mA
Isolation Resistance	R _{iso}	10 ¹²	10 ¹⁴	---	Ω	DC500V 40~60% R.H.
Floating Capacitance	C _{IO}	---	1.0	---	pF	V=0, f=1MHz

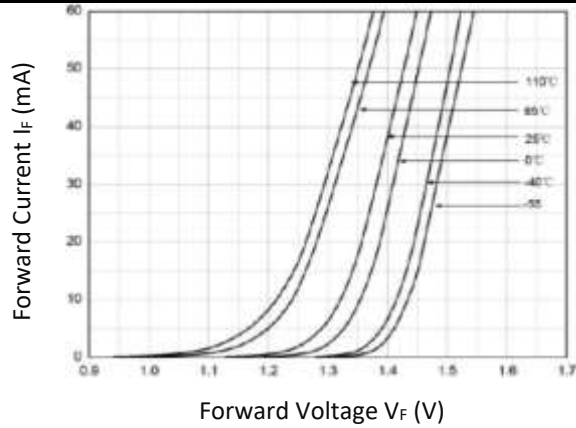
ELECTRICAL CHARACTERISTICS:

Electrical Optical Characteristics:

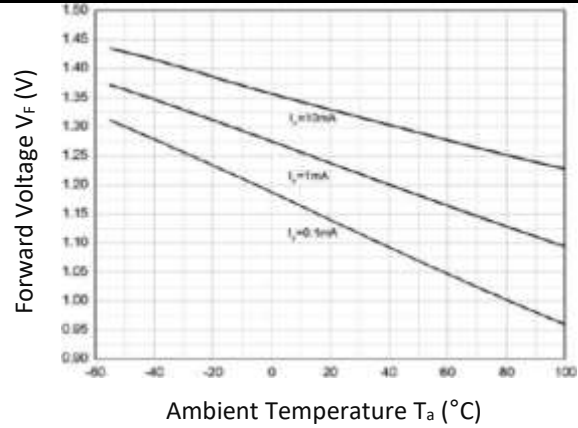
Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
SWITCHING CHARACTERISTICS (T _a =-40 to 85°C, V _{CC} =5V, I _F =7.5mA unless specified otherwise)						
Propagation Delay Time to Output Low Level	T _{PHL}	---	35	75	ns	C _L =15pF, R _L =350Ω T _a =25°C
Propagation Delay Time to Output High Level	T _{PLH}	---	40	75	ns	C _L =15pF, R _L =350Ω T _a =25°C
Pulse Width Distortion	T _{PHL} -PLH	---	5	35	ns	C _L =15pF, R _L =350Ω
Rise Time	t _r	---	27	---	ns	C _L =15pF, R _L =350Ω
Fall Time	t _f	---	7	---	ns	C _L =15pF, R _L =350Ω
Common Mode Transient Immunity at Logic High	CM _H	10000	---	---	V/μs	I _F =7.5mA, V _{OH} =2.0V V _{CM} =400V _{P-P} R _L =350Ω, T _a =25°C
Common Mode Transient Immunity at Logic Low	CM _H	10000	---	---	V/μs	I _F =0mA, V _{OH} =0.8V V _{CM} =400V _{P-P} R _L =350Ω, T _a =25°C

CHARACTERISTIC CURVES:

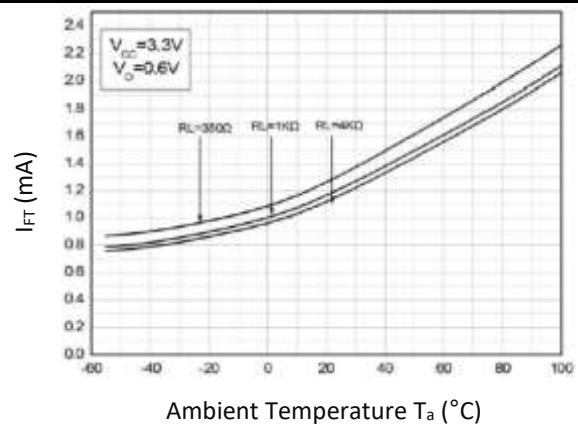
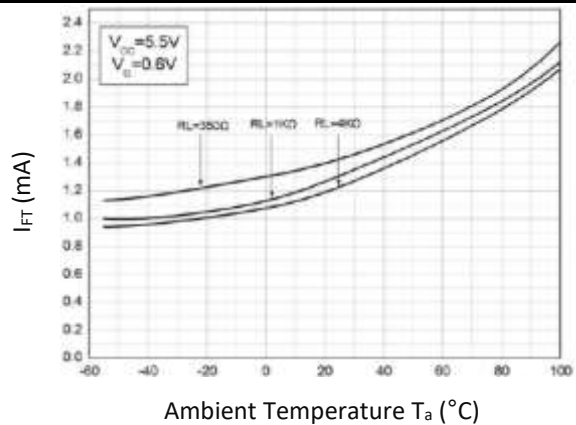
Forward Current v.s. Forward Voltage



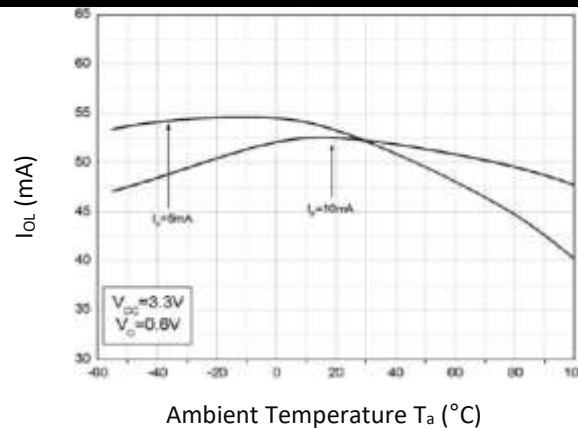
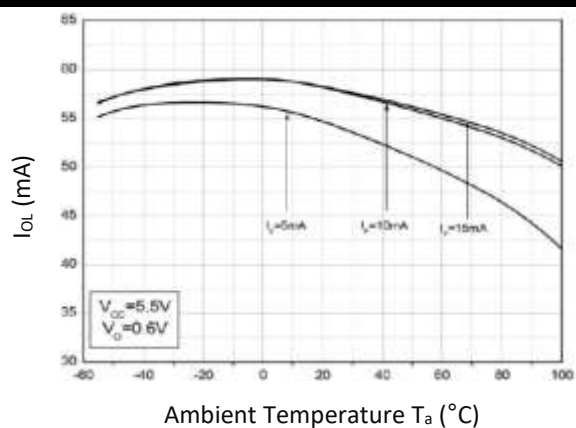
Forward Voltage V_F v.s. Ambient Temperature



Input Threshold Current v.s. Ambient Temperature

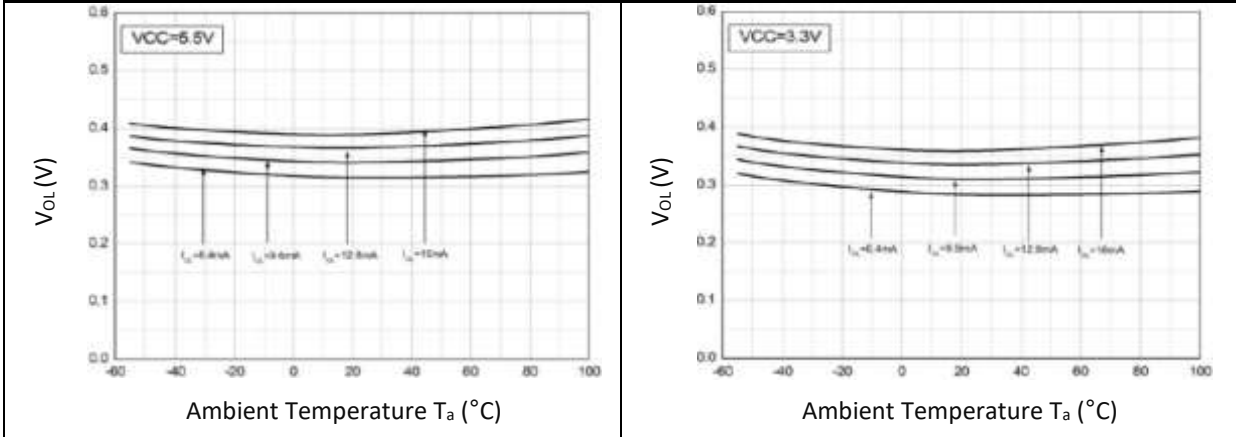


Low Level Output Current v.s. Ambient Temperature

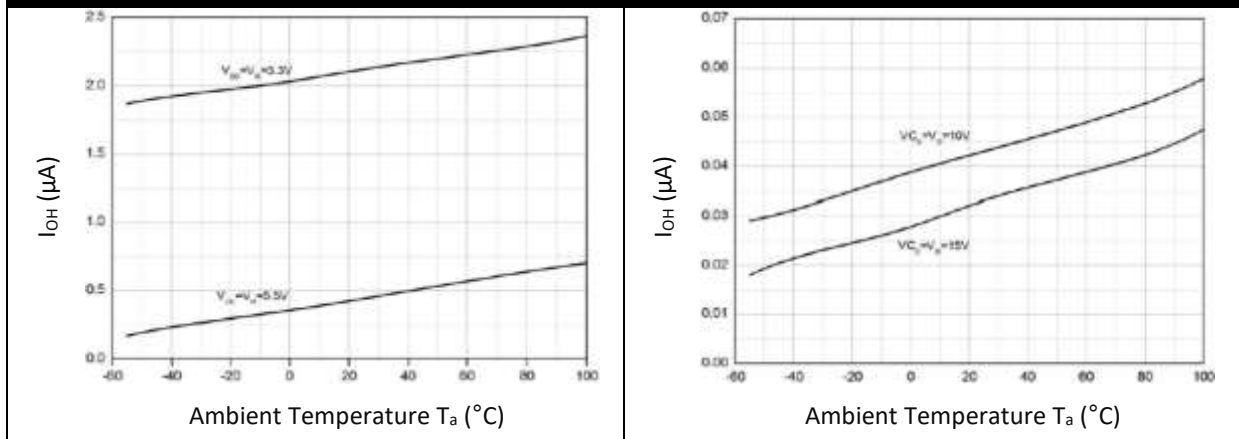


CHARACTERISTIC CURVES:

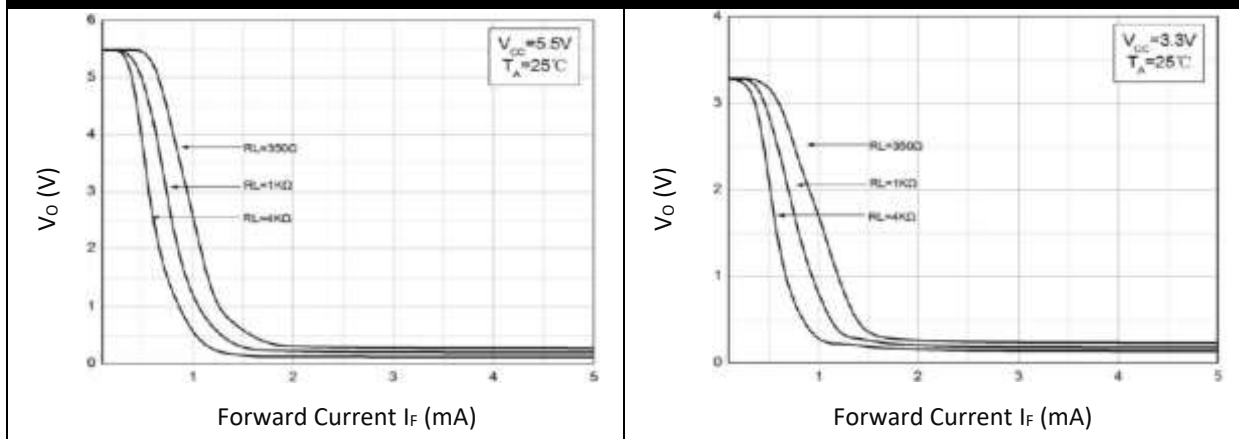
Low Level Output Voltage v.s. Ambient Temperature



High Level Output Current v.s. Ambient Temperature

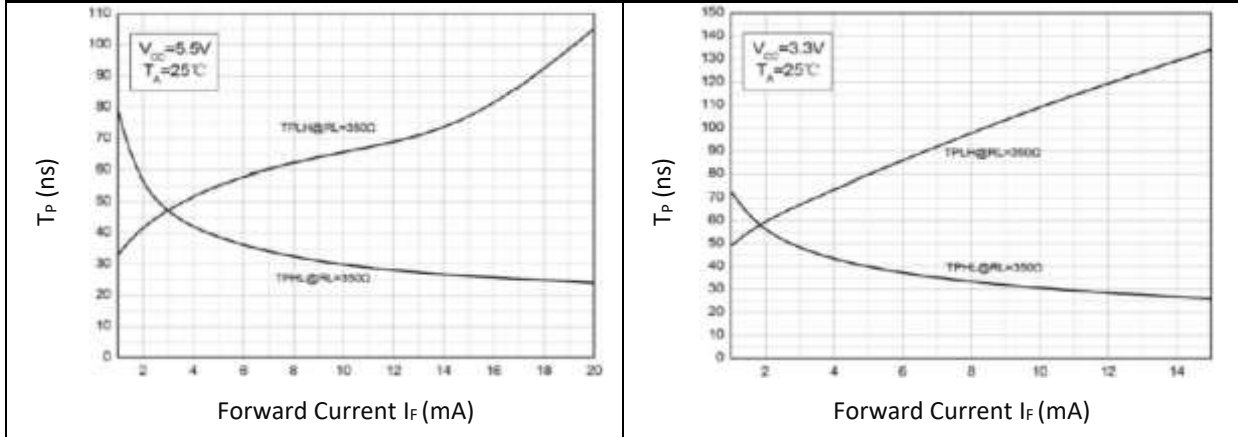


Output Voltage v.s. Forward Current

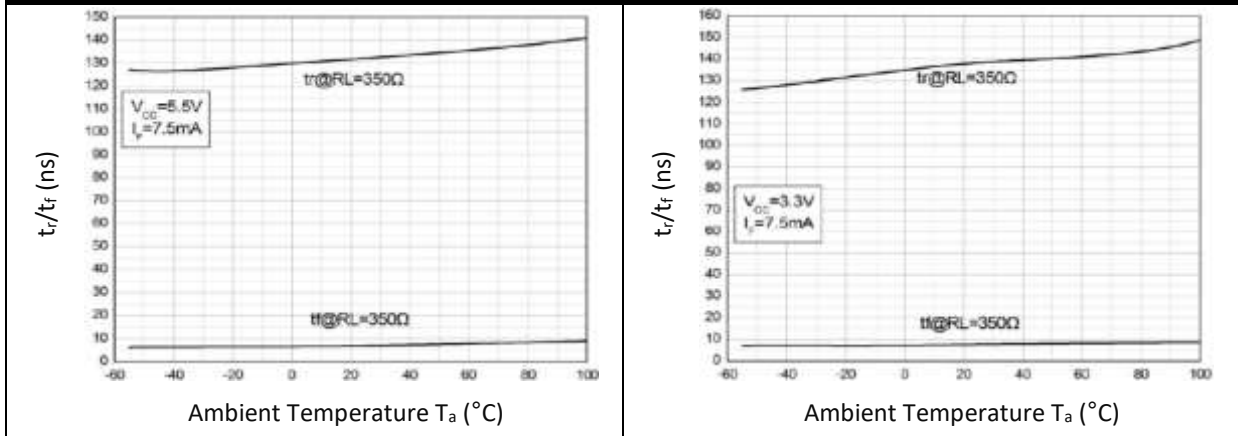


CHARACTERISTIC CURVES:

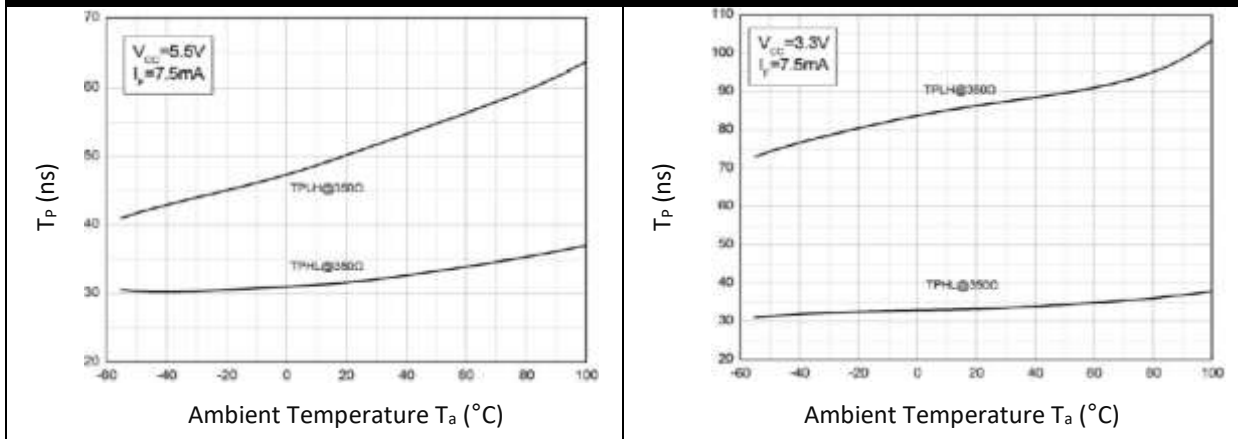
Propagation Delay v.s. Forward Current



Rise and Fall Time v.s. Ambient Temperature

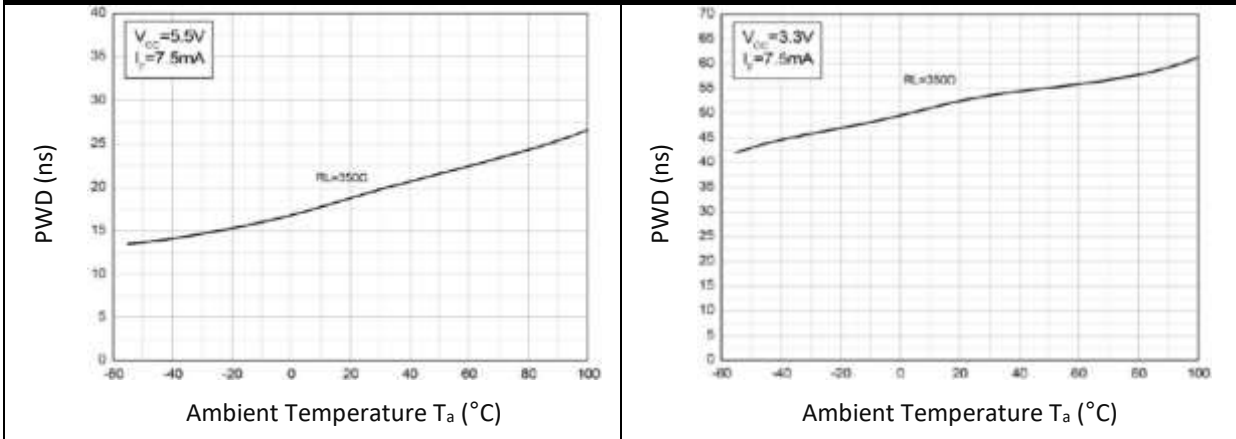


Propagation Delay v.s. Ambient Temperature



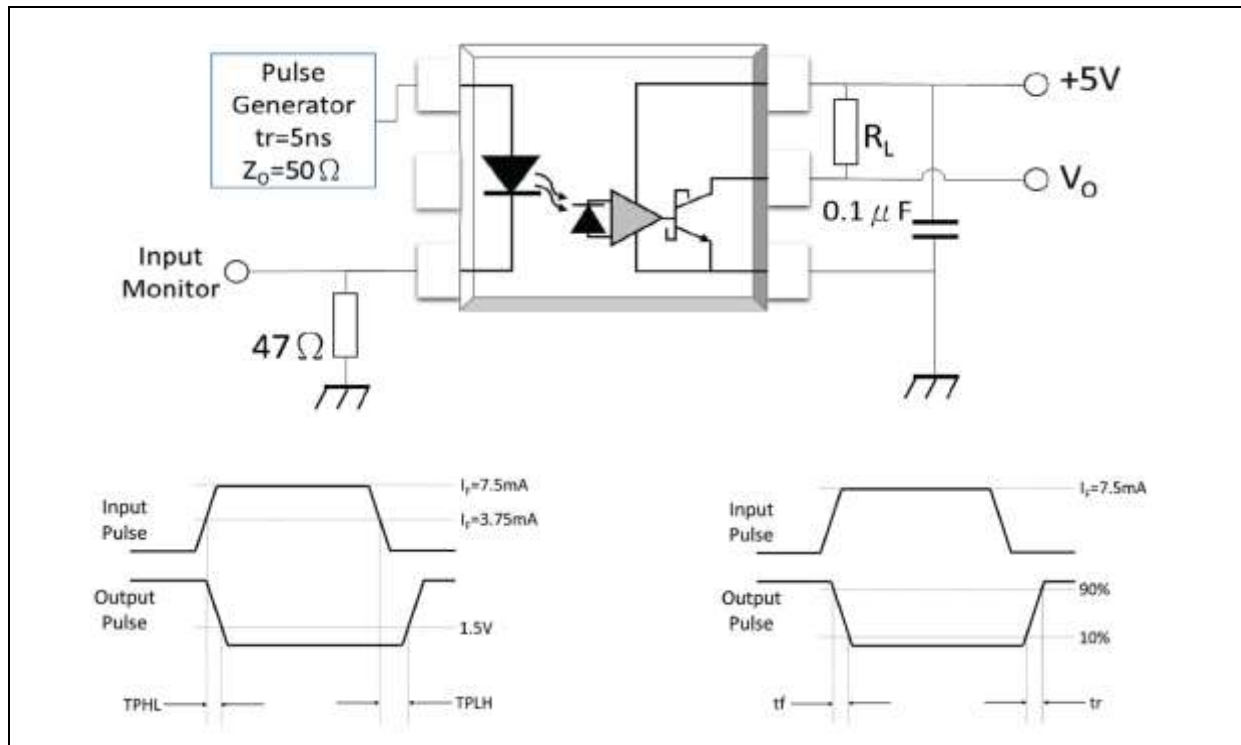
CHARACTERISTIC CURVES:

Pulse Width Distortion v.s. Ambient Temperature

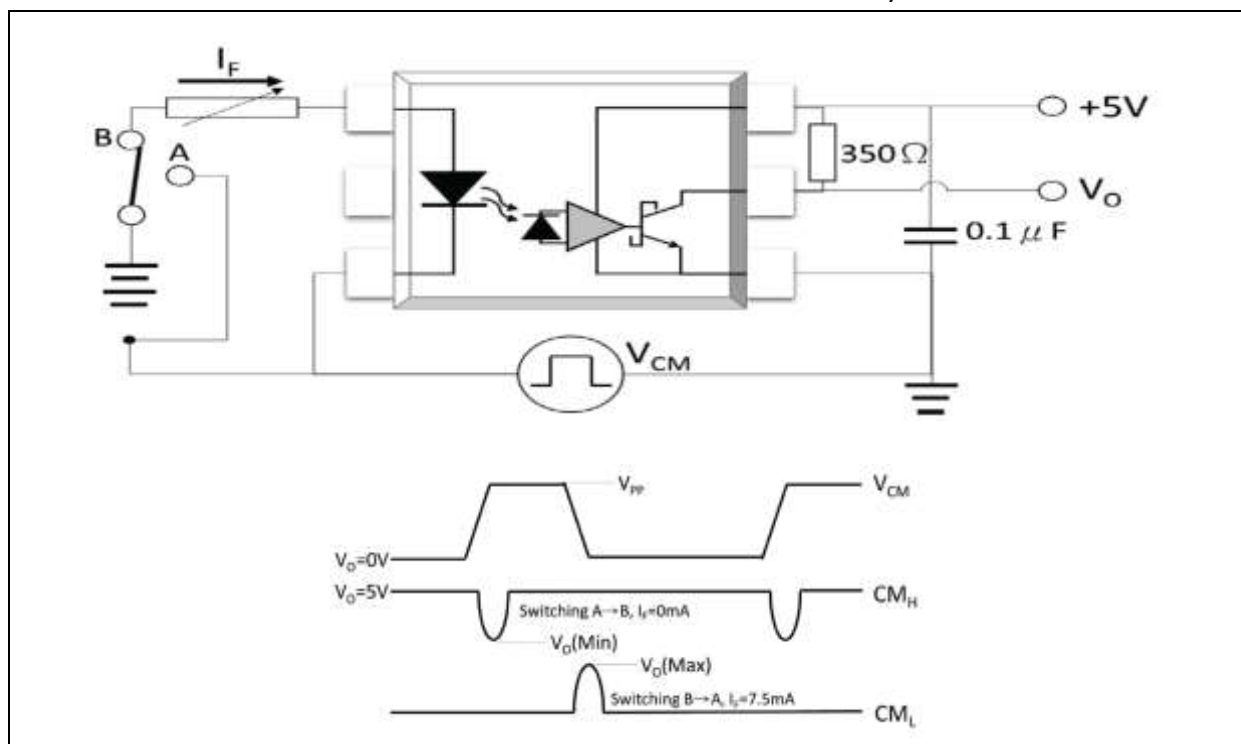


TEST CIRCUIT:

Test Circuit and Waveforms for TPHL, TPLH, tr, tf:

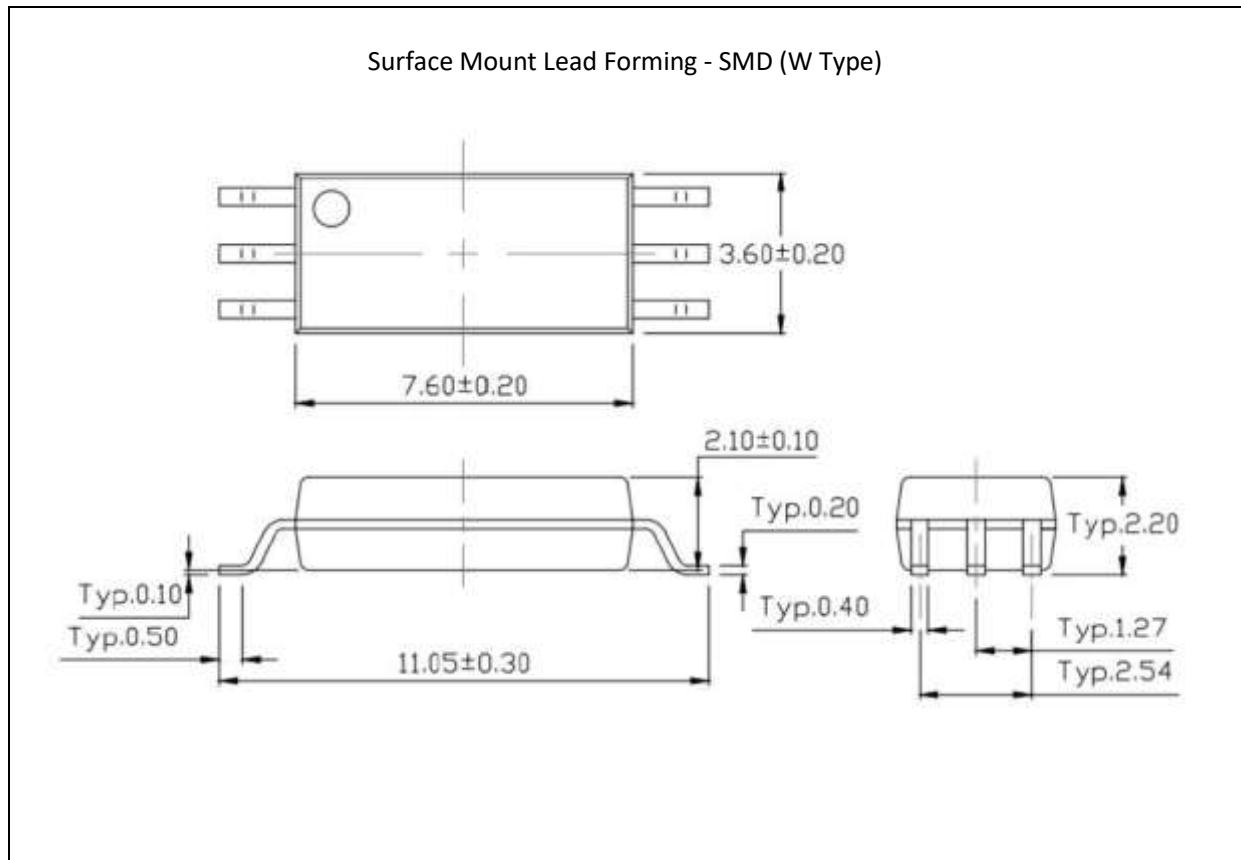


Test Circuit and Waveforms for Common Mode Transient Immunity:



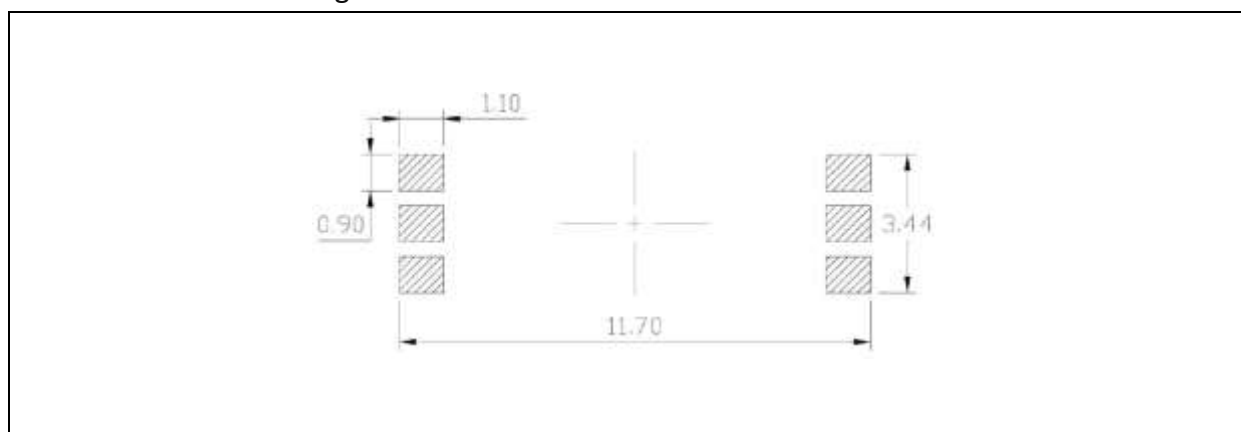
OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).

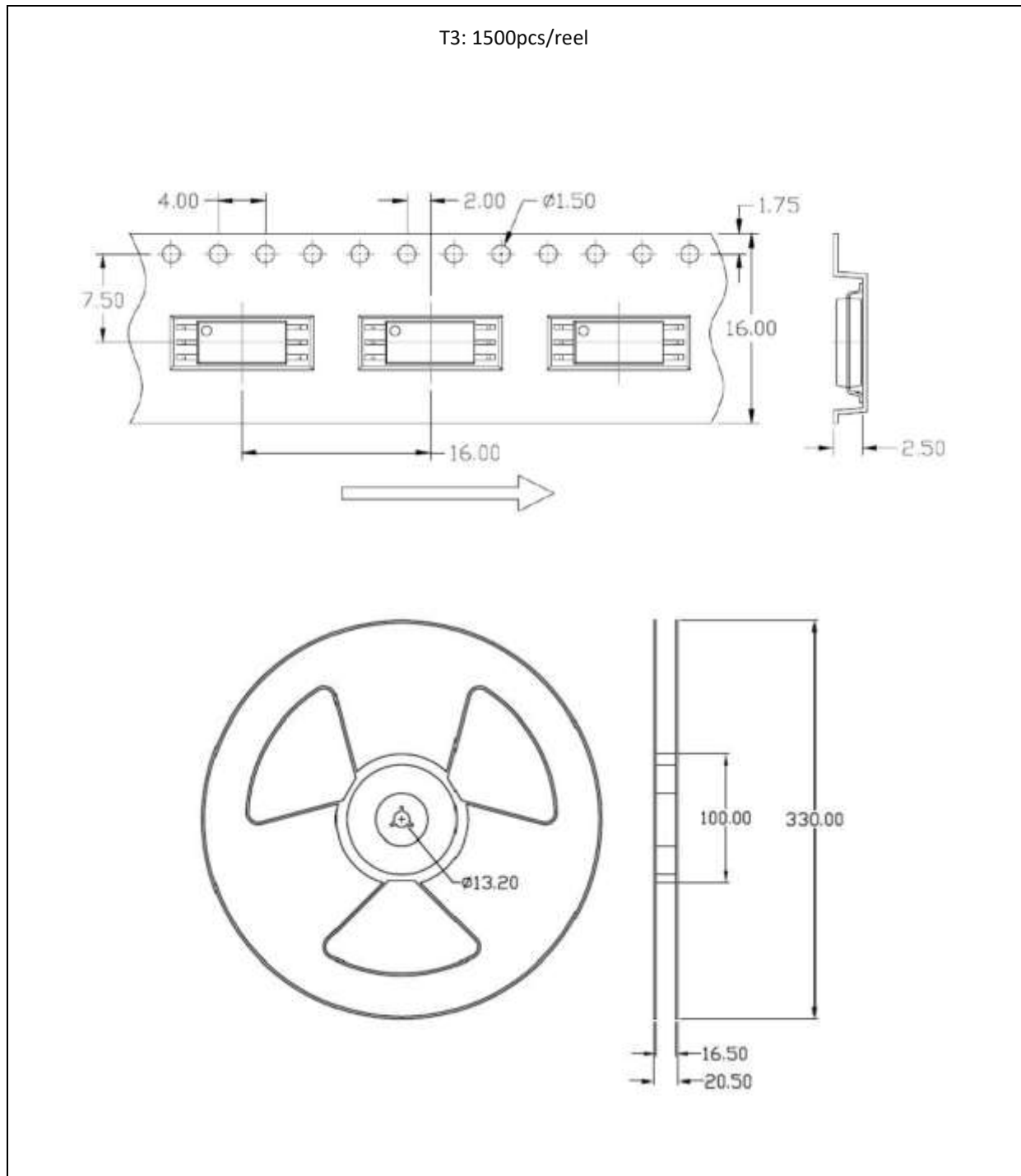
Recommended Soldering Mask:



1. Dimensions are in millimetre (mm).

PACKING SPECIFICATION:

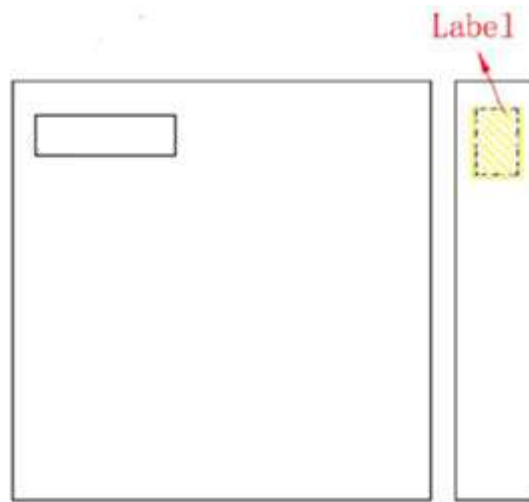
Reel Dimension:



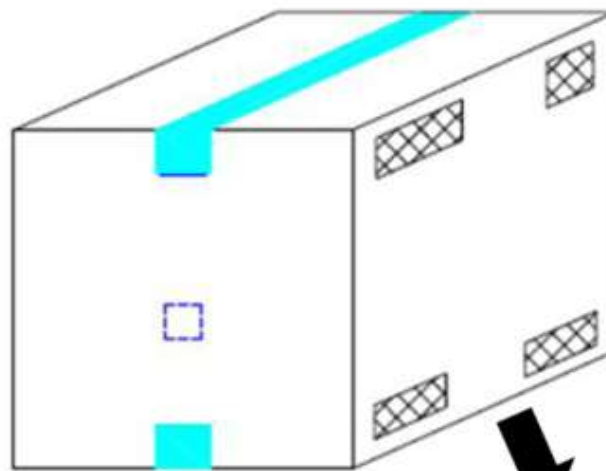
PACKING SPECIFICATION:

Box Dimension:

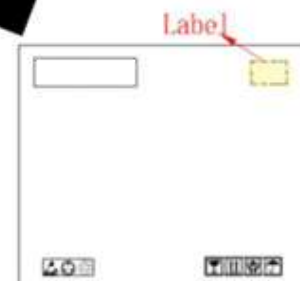
3 reels (4.5Kpcs)/inner box, 5 inner boxes (22.5Kpcs)/carton



● L x W x H = 36cm x 36cm x 6.9cm

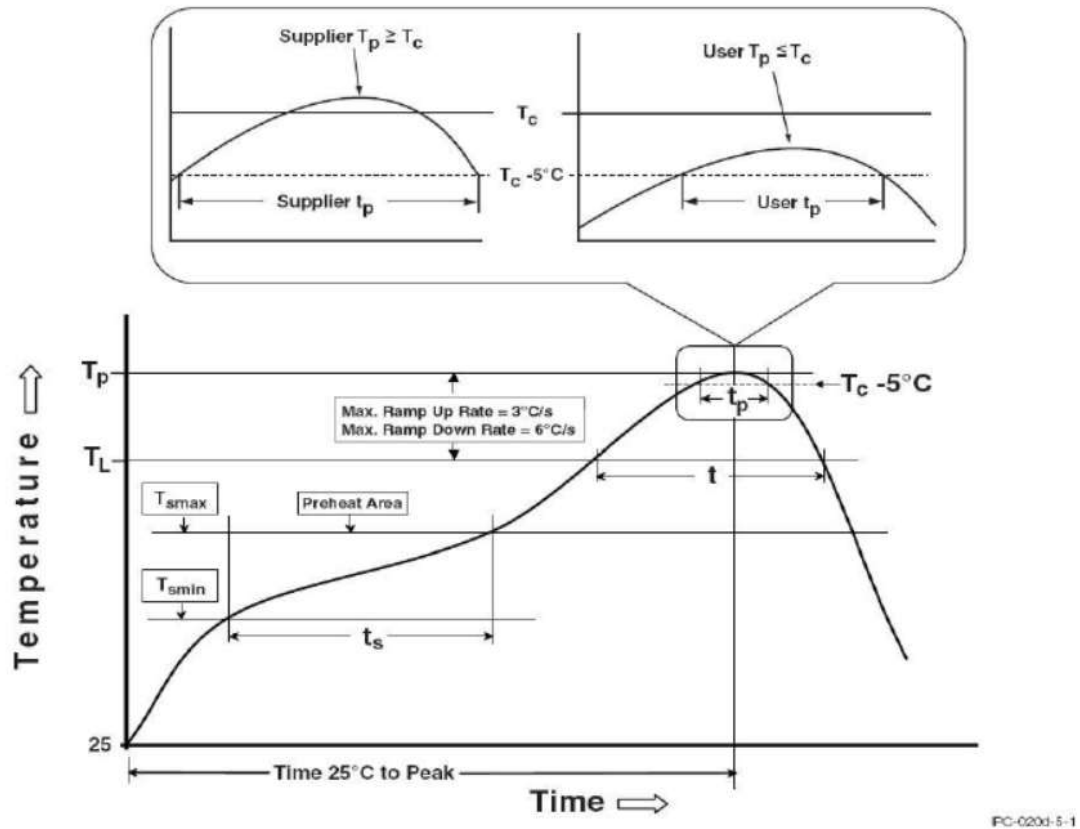


● L x W x H = 45cm x 38cm x 38cm



RECOMMENDED SOLDERING PROFILE:

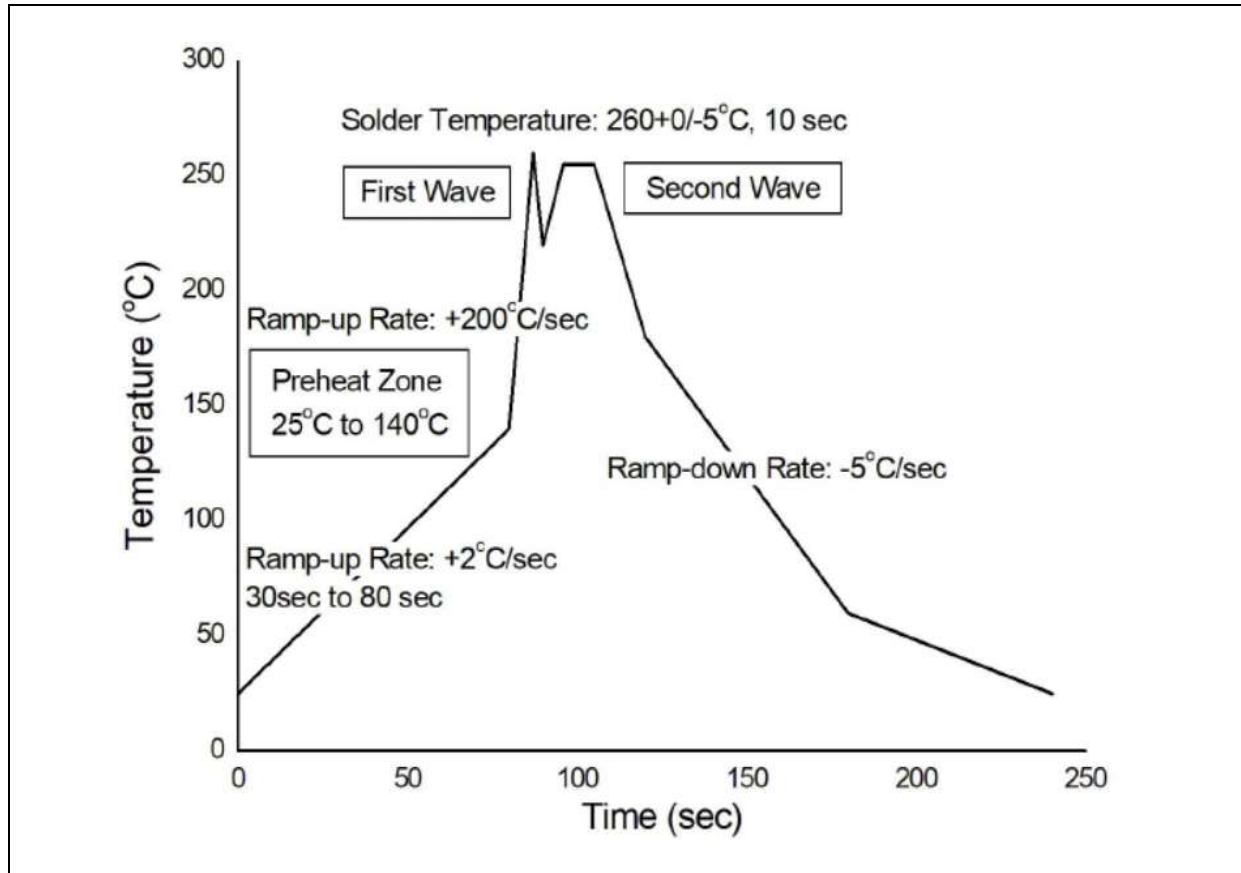
Reflow Information:



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (T_{smin})	100°C	150°C
Temperature Max. (T_{smax})	150°C	200°C
Time (t_s) from (T_{smin} to T_{smax})	60-120 seconds	60-120 seconds
Ramp-up Rate (t_L to t_P)	3°C/second max.	3°C/second max.
Liquidous Temperature (T_L)	183°C	217°C
Time (t_L) Maintained Above (T_L)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235°C +0°C / -5°C	260°C +0°C / -5°C
Time (t_P) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (T_P to T_L)	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

RECOMMENDED SOLDERING PROFILE:

Wave Soldering (JESD22-A111 Compliant):



Hand Soldering:

Soldering Temperature	380±5°C
Soldering Time	3 sec max.

Note:

- One time soldering is recommended for all soldering methods.
- Do not solder more than three times for IR reflow soldering.